

# Flex Circuits

## Products

Type 1- 5  
Sculptured  
Assemblies

Mock Ups  
Sequential Lam.  
TriMetal

## Panel thickness

.003" - .225" (.075mm - 5.70mm)

## Layer count

1 - 20+

## Interconnect Formation Types

Buried  
Dual diameter  
SMT

Blind (laser & mechanical)  
Thru hole  
Filled Vias

## Finished Hole Size

Compliant Pinned .0180" (.460mm)  
Via (A/R dependant) .008" (.200mm)  
Buried vias .008" (.200mm)  
Microvia .004" - .006" (.100-150mm)

## Blind vias aspect ratio

1.25:1

## Through vias

7:1 std 10:1 Adv

## Internal features

Lines/spacing .003"/.003" (.075mm/.075mm)  
Minimum core thickness .001" (0.025mm)

## External features

Lines/spacings .003"/.003" (.075mm/.075mm)

## Production materials

Polyimide - AP, FR  
Adhesive Systems - acrylic, fire retardant, epoxy resin  
FR4 - 24, 26 & 28 Soldermask  
Silver Epoxy Shielding Copper Paste Shielding

## Copper processing

¼ oz. - .400" thick (10.20mm)

## Impedance - single & differential

± 10% standard  
± 7% advanced

## Surface finishes

HASL Immersion Tin  
Reflowed Tin/Lead Immersion Silver  
ENIG OSP-Entek 106  
Ni/Au Bright Tin

